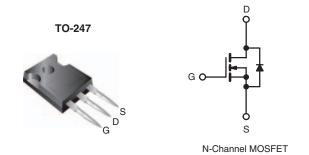


Vishay Siliconix

### **Power MOSFET**

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	50	500			
$R_{DS(on)}\left(\Omega\right)$	V <sub>GS</sub> = 10 V	0.40			
Q <sub>g</sub> (Max.) (nC)	15	0			
Q <sub>gs</sub> (nC)	20	0			
Q <sub>gd</sub> (nC)	80				
Configuration	Single				



#### **FEATURES**

- · Dynamic dV/dt Rating
- Repetitive Avalanche Rated
- Isolated Central Mounting Hole
- · Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Lead (Pb)-free Available

#### **DESCRIPTION**

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-247 package is preferred for commercial-industrial applications where higher power levels preclude the use of TO-220 devices. The TO-247 is similar but superior to the earlier TO-218 package because its isolated mounting hole. It also provides greater creepage distances between pins to meet the requirements of most safety specifications.

ORDERING INFORMATION	
Package	TO-247
Lead (Pb)-free	IRFP450PbF
Leau (FD)-liee	SiHFP450-E3
SnPb	IRFP450
SIFD	SiHFP450

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			$V_{DS}$	500	V	
Gate-Source Voltage			$V_{GS}$	± 20	1 V	
Continuous Drain Current	V <sub>GS</sub> at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	1-	14	А	
	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 100 °C	ID	8.7		
Pulsed Drain Current <sup>a</sup>			I <sub>DM</sub>	56	i	
Linear Derating Factor				1.5	W/°C	
Single Pulse Avalanche Energy <sup>b</sup>			E <sub>AS</sub>	760	mJ	
Repetitive Avalanche Current <sup>a</sup>			I <sub>AR</sub>	8.7	Α	
Repetitive Avalanche Energy <sup>a</sup>			E <sub>AR</sub>	19	mJ	
Maximum Power Dissipation	T <sub>C</sub> = 25 °C		$P_{D}$	190	W	
Peak Diode Recovery dV/dtc			dV/dt	3.5	V/ns	
Operating Junction and Storage Temperature Range			T <sub>J</sub> , T <sub>stg</sub>	- 55 to + 150	00	
Soldering Recommendations (Peak Temperature)	for '	10 s		300 <sup>d</sup>	°C	
Mounting Torque	6.22.04.1	0.00 140		10	lbf ⋅ in	
	6-32 or M3 screw			1.1	N · m	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b.  $V_{DD}$  = 50 V, starting  $T_J$  = 25 °C, L = 7.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AS}$  = 14 A (see fig. 12).
- c.  $I_{SD} \le 14$  A,  $dI/dt \le 130$  A/ $\mu$ s,  $V_{DD} \le V_{DS}$ ,  $T_J \le 150$  °C.
- d. 1.6 mm from case.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply

# IRFP450, SiHFP450

# Vishay Siliconix



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R <sub>thJA</sub>	-	40		
Case-to-Sink, Flat, Greased Surface	R <sub>thCS</sub>	0.24	-	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	-	0.65		

<b>SPECIFICATIONS</b> T <sub>J</sub> = 25 °C,	unless other	vise noted					
PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNIT	
Static						•	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference t	o 25 °C, I <sub>D</sub> = 1 mA	-	0.63	-	V/°C
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2.0	-	4.0	٧
Gate-Source Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ± 20 V		-	-	± 100	nA
Zone Oata Walkana Busin Oursel	I <sub>DSS</sub>	V <sub>DS</sub> = 500 V, V <sub>GS</sub> = 0 V		-	-	25	
Zero Gate Voltage Drain Current		V <sub>DS</sub> = 400 V, V	<sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	250	μΑ
Drain-Source On-State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 8.4 A <sup>b</sup>	-	-	0.40	Ω
Forward Transconductance	9 <sub>fs</sub>	V <sub>DS</sub> = 5	0 V, I <sub>D</sub> = 8.4 A <sup>b</sup>	9.3	-	-	S
Dynamic				I.	•	•	
Input Capacitance	C <sub>iss</sub>	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. 5}$		-	2600	-	pF
Output Capacitance	C <sub>oss</sub>			-	720	-	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	340	-	
Total Gate Charge	Qg		I <sub>D</sub> = 14 A, V <sub>DS</sub> = 400 V, see fig. 6 and 13 <sup>b</sup>	-	-	150	nC
Gate-Source Charge	$Q_{gs}$	V <sub>GS</sub> = 10 V		-	-	20	
Gate-Drain Charge	Q <sub>gd</sub>			-	-	80	
Turn-On Delay Time	t <sub>d(on)</sub>	$V_{DD}$ = 250 V, $I_{D}$ = 14 A, $R_{G}$ = 6.2 Ω, $R_{D}$ = 17 Ω, see fig. 10 <sup>b</sup>		-	17	-	ns
Rise Time	t <sub>r</sub>			-	47	-	
Turn-Off Delay Time	t <sub>d(off)</sub>			-	92	-	
Fall Time	t <sub>f</sub>			-	44	-	
Internal Drain Inductance	L <sub>D</sub>	Between lead, 6 mm (0.25") from package and center of die contact		-	5.0	-	- nH
Internal Source Inductance	L <sub>S</sub>			-	13	-	
Drain-Source Body Diode Characteristic	s			I.			
Continuous Source-Drain Diode Current	I <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	14	
Pulsed Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			-	-	56	A
Body Diode Voltage	V <sub>SD</sub>	$T_J = 25  ^{\circ}\text{C},  I_S = 14  \text{A},  V_{GS} = 0  \text{V}^{\text{b}}$		-	-	1.4	V
Body Diode Reverse Recovery Time	t <sub>rr</sub>	$T_J = 25 \text{ °C}, I_F = 14 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s}^b$		-	540	810	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>			-	4.8	7.2	μС
Forward Turn-On Time	t <sub>on</sub>	Intrinsic turn-on time is negligible (turn-on is dominated by L <sub>S</sub> and I				L <sub>D</sub> )	

#### Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- b. Pulse width  $\leq$  300  $\mu$ s; duty cycle  $\leq$  2 %.



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

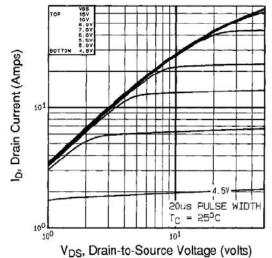


Fig. 1 - Typical Output Characteristics, T<sub>C</sub> = 25 °C

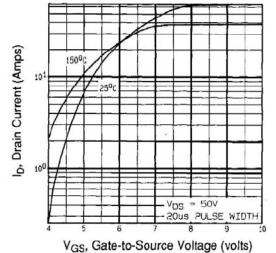


Fig. 3 - Typical Transfer Characteristics

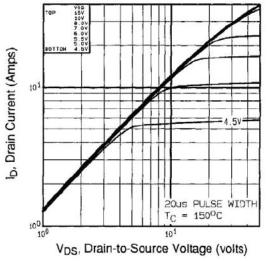


Fig. 2 - Typical Output Characteristics,  $T_C = 150$  °C

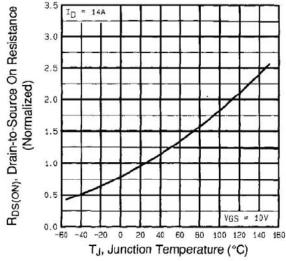


Fig. 4 - Normalized On-Resistance vs. Temperature

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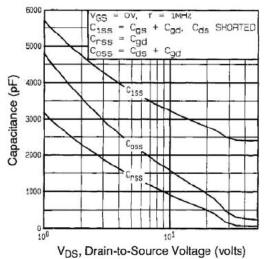


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

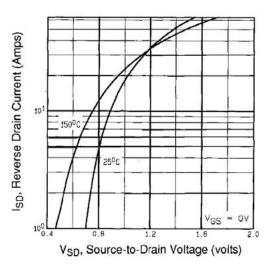


Fig. 7 - Typical Source-Drain Diode Forward Voltage

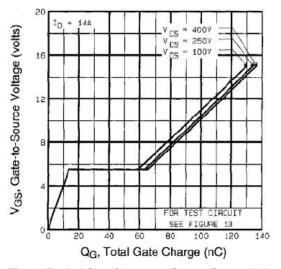


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

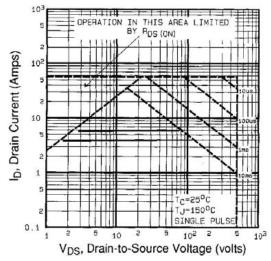


Fig. 8 - Maximum Safe Operating Area





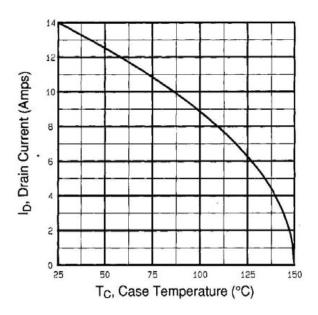


Fig. 9 - Maximum Drain Current vs. Case Temperature

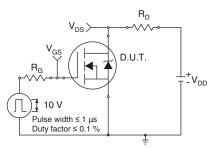


Fig. 10a - Switching Time Test Circuit

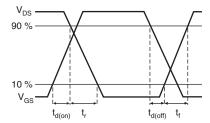


Fig. 10b - Switching Time Waveforms

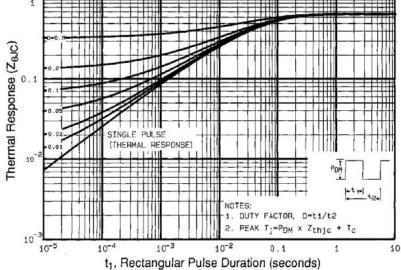


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

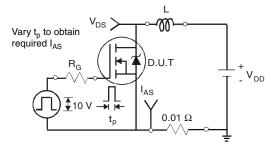


Fig. 12a - Unclamped Inductive Test Circuit

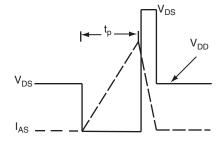


Fig. 12b - Unclamped Inductive Waveforms

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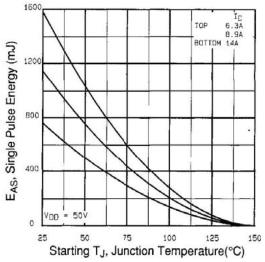


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

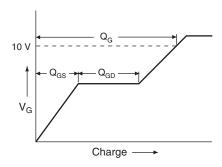


Fig. 13a - Basic Gate Charge Waveform

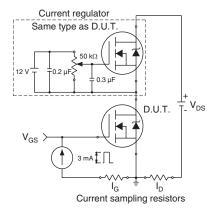
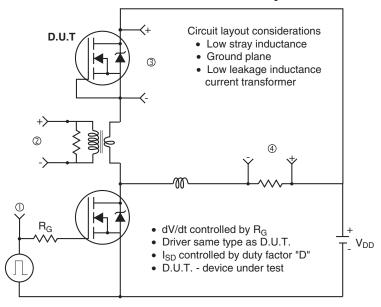


Fig. 13b - Gate Charge Test Circuit



## Peak Diode Recovery dV/dt Test Circuit



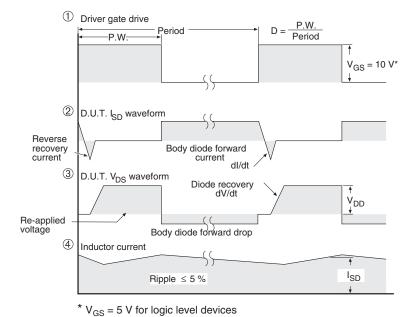


Fig. 14 - For N-Channel

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Revision: 11-Mar-11